

Patent Abstracts of Japan

PUBLICATION NUMBER : 10163263
PUBLICATION DATE : 19-06-98

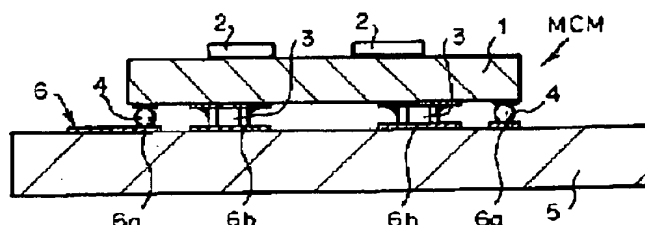
APPLICATION DATE : 29-11-96
APPLICATION NUMBER : 08319467

APPLICANT : NEC CORP;

INVENTOR : SUZUKI MOTOHARU;

INT.CL. : H01L 21/60 H01L 25/04 H01L 25/18

TITLE : MOUNTING STRUCTURE FOR
MULTICHIP MODULE



ABSTRACT : **PROBLEM TO BE SOLVED:** To prevent a multichip module having a plurality of chip components mounted from sinking due to its own weight caused by the crush of a BGA solder ball, and to prevent a chip component from coming into contact with the wiring pattern of a mother board and short-circuiting, on the occasion of mounting the multichip module on the mother board using BGA solder balls.

SOLUTION: Under the condition of mounting a multichip module MCM having chip components 2, 3 mounted on a board 1, on a mother board 5 by BGA solder balls 4, the chip component 3 is in contact with a mounting pad 6b as a dummy pad formed on the mother board 5. It becomes unnecessary to provide a clearance between the chip component 3 and the mother board 5, and it becomes possible to reduce the height of the mounting construction and to prevent the short circuit of the chip component 3 with wirings 6 on the mother board 5. It becomes unnecessary to increase the diameter of the BGA solder balls 4 more than needed to secure a clearance, and to use BGA solder balls containing metal cores, so it becomes possible to realize the size reduction of the mounting construction and the facilitation of constitution.

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(11)Publication number : 10-163263

(43)Date of publication of application : 19.06.1998

(51)Int.Cl.

H01L 21/60

H01L 25/04

H01L 25/18

(21)Application number : 08-319467

(71)Applicant : NEC CORP

(22)Date of filing : 29.11.1996

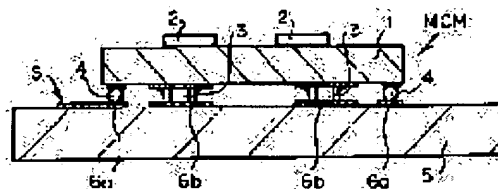
(72)Inventor : SUZUKI MOTOHARU

(54) MOUNTING STRUCTURE FOR MULTICHIP MODULE

(57)Abstract:

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LEGAL STATUS

[Date of request for examination] 29.11.1996

[Date of sending the examiner's decision of rejection]

[Kind of final disposal of application other than the examiner's decision of rejection or application converted registration]

[Date of final disposal for application]

[Patent number] 2845227

[Date of registration] 30.10.1998

[Number of appeal against examiner's decision of rejection]

[Date of requesting appeal against examiner's]

Searching PAJ

decision of rejection]

[Date of extinction of right]

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